

Features

- Low drain-source on-resistance: $R_{DS(ON)}=0.25\Omega(\text{typ})$
- Easy to control gate switching
- Enhancement mode: $V_{th} = 2.0$ to $4.0V$
- 100% avalanche tested
- Built-in ESD Diode
- RoHS compliant

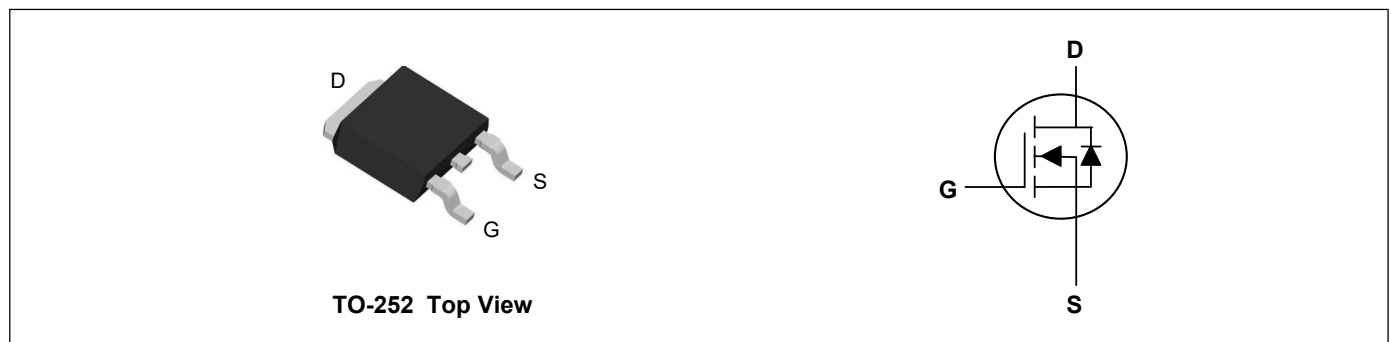
Key Performance Parameters



Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	700	V
$R_{DS(ON),max}$	280	m Ω
I_D	14.6	A
$Q_{g,typ}$	25	nC
I_{DM}	44	A

Applications

- Switch Mode Power Supply (SMPS)
- TV power & LED Lighting Power
- AC to DC Converters
- Telecom



Absolute Maximum Ratings($T_C=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	700	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ¹	$I_D @ T_C=25^\circ\text{C}$	14.6	A
Continuous Drain Current ¹	$I_D @ T_C=100^\circ\text{C}$	9.2	A
Pulsed Drain Current ²	I_{DM}	44	A
Single Pulse Avalanche Energy ⁴	EAS	375	mJ
Avalanche Current	I_{AS}	5	A
MOSFET dv/dt ruggedness, $V_{DS} = 0 \dots 480V$	dv/dt	50	V/ns
Reverse diode dv/dt ³ $V_{DS}=0 \dots 480V, I_{DS} \leq I_D$		15	
Total Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	120	W
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-Ambient (Max)	$R_{\theta JA}$	62	$^\circ\text{C/W}$
Thermal Resistance Junction-Case (Max)	$R_{\theta JC}$	1.0	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	700	---	---	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=7.5A$	---	250	280	m Ω
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=220\mu A$	2.0	---	4.0	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=700V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=700V, V_{GS}=0V, T_J=125^{\circ}\text{C}$	---	---	100	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	± 1	μA
Total Gate Charge	Q_g	$V_{DD}=400V, V_{GS}=10V, I_D=7.5A$	---	25	---	nC
Gate-Source Charge	Q_{gs}		---	5.2	---	
Gate-Drain Charge	Q_{gd}		---	9.3	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=400V, R_G=15\Omega, I_D=7.5A$	---	17	---	ns
Rise Time	T_r		---	18	---	
Turn-Off Delay Time	$T_{d(off)}$		---	89	---	
Fall Time	T_f		---	20	---	
Input Capacitance	C_{iss}	$V_{DS}=100V, V_{GS}=0V, f=1\text{MHz}$	---	1100	---	pF
Output Capacitance	C_{oss}		---	41	---	
Reverse Transfer Capacitance	C_{rss}		---	2.1	---	

Drain-Source Diode Characteristics

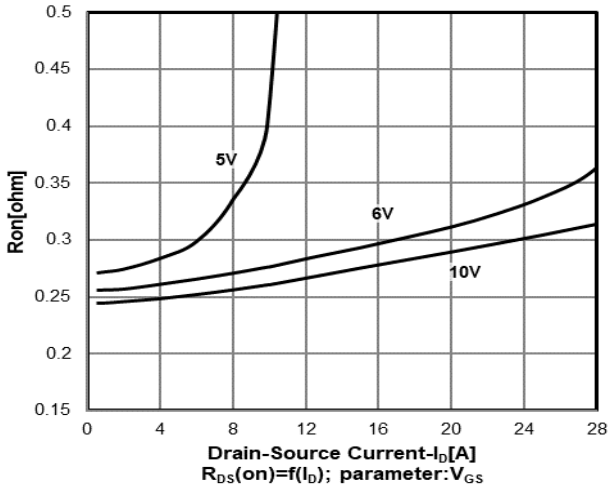
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current	I_S	$T_C=25^{\circ}\text{C}$	---	---	14.6	A
Pulsed Source Current	I_{SM}		---	---	44	A
Diode Forward Voltage	V_{SD}	$V_G=0V, I_S=15A, T_J=25^{\circ}\text{C}$	---	0.9	1.4	V
Reverse Recovery Time	t_{rr}	$V_{DD}=400V, I_S=7.5A, di_f/dt=100A/\mu s$	---	295	---	ns
Reverse Recovery Charge	Q_{rr}		---	3.1	---	μC
Peak Reverse Recovery Current	I_{rrm}		---	20.5	---	A

Note:

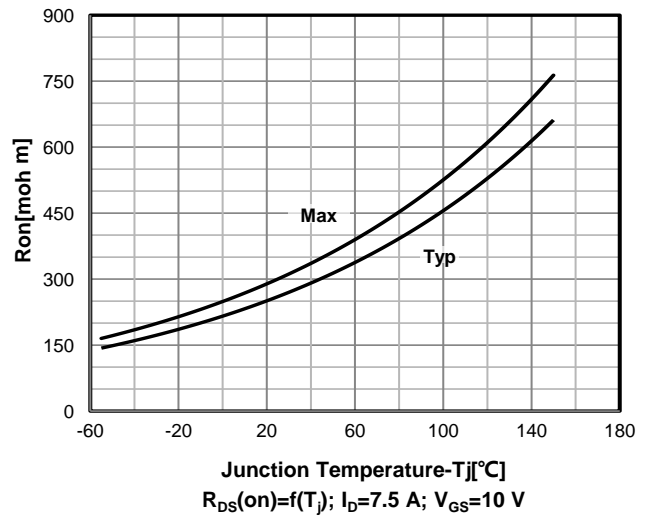
- Limited by $T_{J,max}$. Maximum Duty Cycle $D = 0.50$
- Pulse width t_p limited by $T_{J,max}$
- Identical low side and high side switch with identical R_G
- $V_{DD}=50V, R_G=25\Omega, I_{AS}=I_D, L=30\text{mH}$

Typ. drain-source on-state resistance

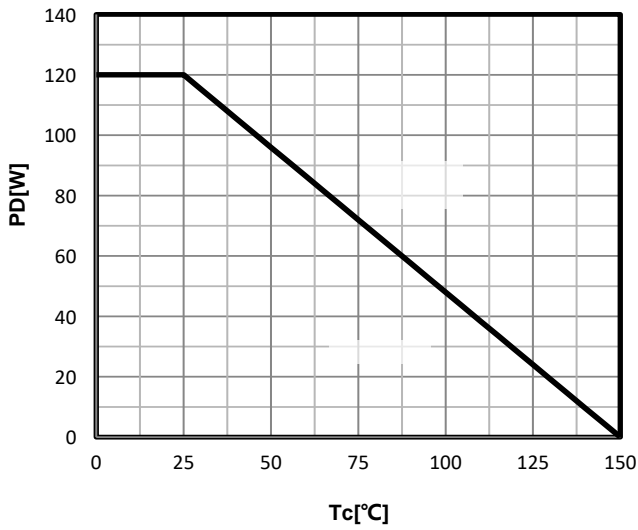
Typ. drain-source on-state resistance



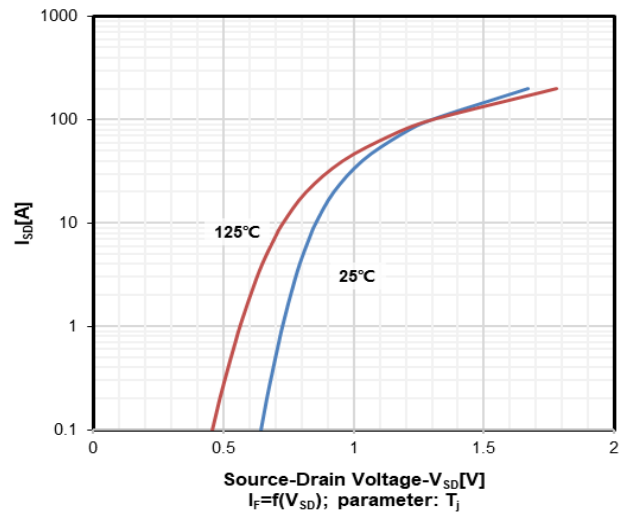
On resistance vs temperature



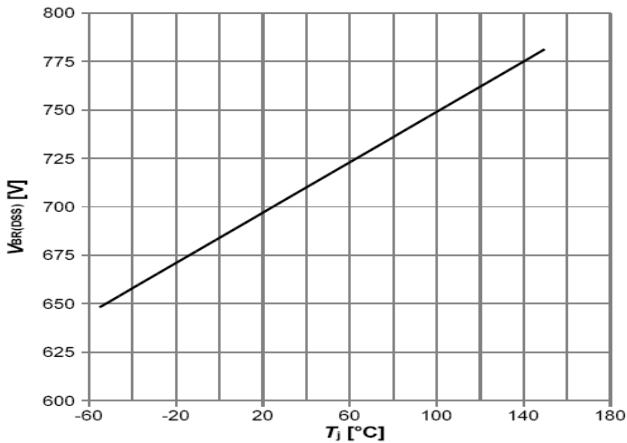
Power dissipation



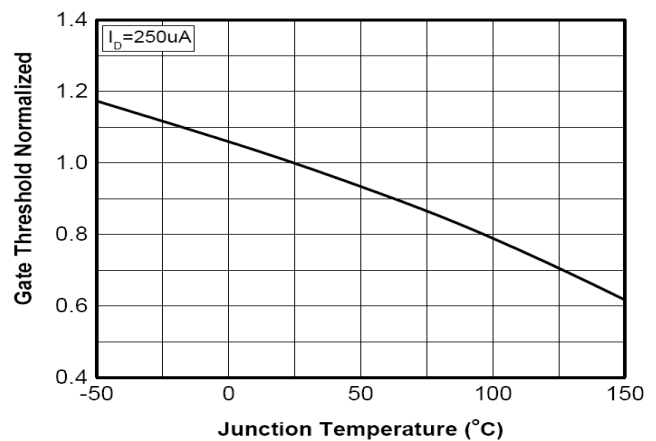
Forward characteristics of reverse diode



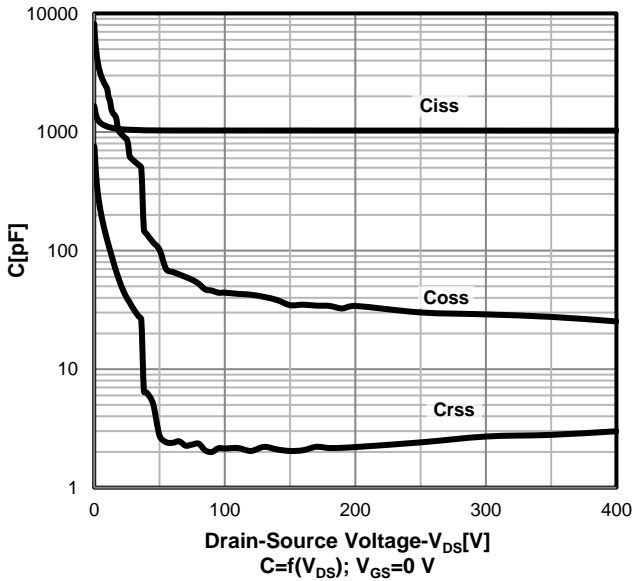
Drain-source breakdown voltage



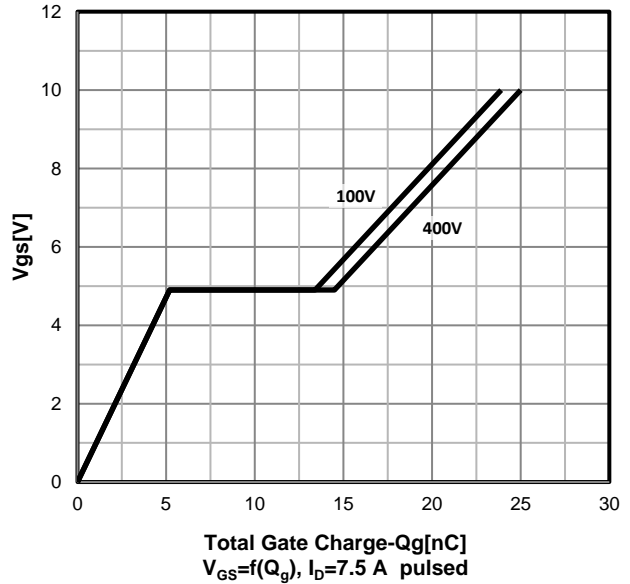
Normalized $V_{GS(th)}$ characteristics



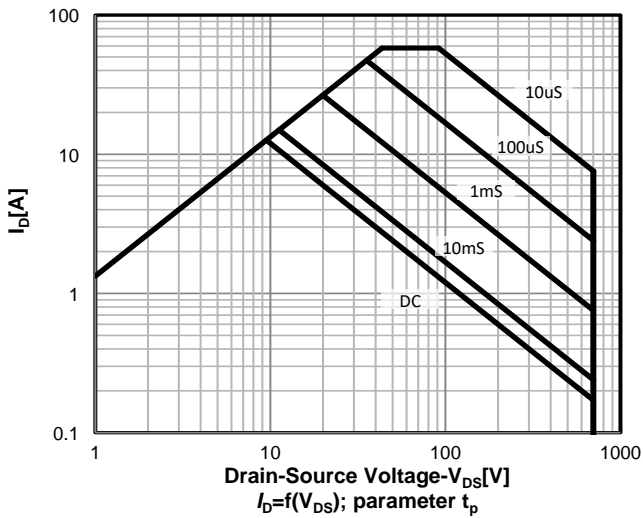
Typ. capacitances



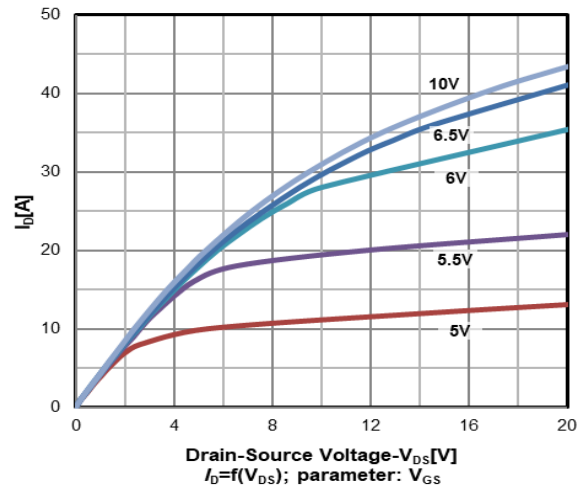
Typ. gate charge characteristics



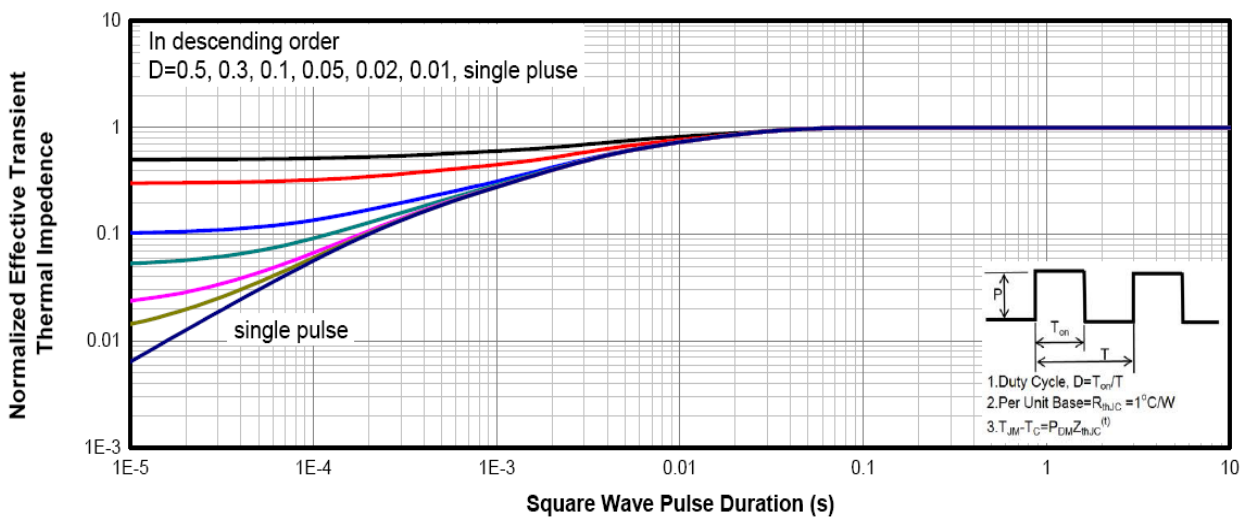
Safe operating area $T_C=25\text{ }^\circ\text{C}$



Typ. output characteristics $T_J=25\text{ }^\circ\text{C}$



Max. transient thermal impedance



TO-252 Package Outline Dimensions

